| ASSOCIATION CONNECTING<br>ELECTRONICS INDUSTRIES® | <b>Aterial Composit</b><br>Copyright 2005. IPC, H<br>rnational and Pan-Am | ion Decla<br>Bannockburn<br>Berican copy | n, Illinois. A<br>right conven  | ll rights reserved u tions. | nder both               | This docume<br>level parts, t                                     | ent is a declaration en declaration | on of the substancompasses all | nces within the r<br>lower level mate | nanufacture<br>rials for whi | r listed item.<br>ich the manut | Note: if<br>acturer l | the item is an as has engineering | sembly with low responsibility. |
|---|---|--|---------------------------------|-----------------------------|-------------------------|---|---|--------------------------------|---------------------------------------|------------------------------|---------------------------------|-----------------------|-----------------------------------|---------------------------------|
| /5/2/1  |   |  |                                 |                             | Form Type<br>Distribute | * Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Mater |   |                                |                                       | ous Material                 | ials and Mfg Information        |                       |                                   |                                 |
| upplier Informatior                               | 1   |  |                                 |                             |                         |   |   |                                |                                       |                              |                                 |                       |                                   |                                 |
| Company name*                                     |   |  | Company unique ID               |                             |                         |   | Unique ID Authority   |                                |                                       |                              | Response Date*                  |                       |                                   |                                 |
| onsemi  |   |  |                                 |                             |                         |   |   |                                |                                       |                              | 2024-05-16                      |                       |                                   |                                 |
| Contact Name                                      |   |  | Title - Contact                 |                             |                         |   | Phone - Contact*  |                                |                                       |                              | Email - Contact*                |                       |                                   |                                 |
| Product-Env-Stewards                              |   |  | Product Enviro Compliance       |                             |                         |   | NA  |                                |                                       |                              | Product-Env-Stewards@onsemi.com |                       |                                   |                                 |
| Authorized Representative*                        |   |  | Title - Representative          |                             |                         |   | Phone - Representative*   |                                |                                       |                              | Email - Representative*         |                       |                                   |                                 |
| Product-Env-Stewards                              |   |  | Product Enviro Compliance       |                             |                         |   | NA  |                                |                                       |                              | Product-Env-Stewards@onsemi.com |                       |                                   |                                 |
| Requester Item                                    | Requester Item Number Mfr Iter  |  | n Number Mfr Item Name          |                             |                         |   | Effective Date  | Version                        | Manufacturi                           | Manufacturing Site           |                                 | ht*                   | UOM                               | Unit Type                       |
|   |   | FGH50T65SQD-F155                         |                                 | FS4TIGBT TO247 50A 650V     |                         |   | 2024-05-16  |                                | СРА                                   | СРА                          |                                 | .925                  | mg                                | Each                            |
| Ianufacturing Proc                                | cess Information  |  |                                 |                             |                         |   |   | -                              |                                       |                              |                                 |                       |                                   |                                 |
| Terminal Plating / Grid Array Material            |   | 1 Terr                                   | Ferminal Base Alloy J-STD-020 M |                             | -STD-020 MS             | L Rating  | Peak Process Body Temperature   |                                | erature Max Tin                       | ne at Peak T                 | emperature                      | Numbe                 | er of Reflow Cyc                  | les                             |
| Matte Tin (Sn) - annealed                         |   | CU                                       | CU Alloy NA                     |                             |                         | 0 C   |   | 30                             | <b>30</b> sec                         |                              | 3                               |                       |                                   |                                 |
| omments   |   |  |                                 |                             |                         |   |   |                                |                                       |                              |                                 |                       |                                   |                                 |
|   |   |  |                                 |                             |                         |   |   |                                |                                       |                              |                                 |                       |                                   |                                 |
| or more information reg                           | arding material com   | position ple                             | ease refer to                   | page 3                      |                         |   |   |                                |                                       |                              |                                 |                       |                                   |                                 |

| RoHS Material Composition Declaration  |  |   |   | Declaration Type *  | Detailed  |  |  |  |  |  |  |  |
|--|--|---|---|---|---|--|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | (Pb), Mercury (Hg), Hexavalent Chro  | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP). |   |   |   |  |  |  |  |  |  |  |
| cadmium, hexavalentchromium, polybromina<br>contains a RoHS restricted substance inexces<br>encompass all such components. Supplier cer<br>as of the date that Supplier completes this for<br>Company acknowledges that Supplier may h<br>independently verified information provided<br>certification in this paragraph. If the Company | ated biphenyls and/or polybrominated dip<br>s of an applicable quantity limit, please in<br>iffies that it gathered the information it pr<br>m.Supplier acknowledges that Company<br>ave relied on informationprovided by oth<br>by others, Supplier agrees that, at a minir<br>and the Supplier enter into a written agr<br>esource of the Supplier's liability and the | henyl ethers (each a "RoHS restricted substa<br>ndicate below which, if any, RoHS exemption<br>ovides in this form using appropriate methoo<br>will rely on this certification in determining<br>ers in completing this form, and that Supplie<br>num, itssuppliers have provided certification<br>eement with respect to the identified part, the<br>Company's remedies for issues that arise reg                                | nce") in exco<br>n you believe<br>ls to ensure i<br>the compliar<br>r may not ha<br>s regarding t<br>terms and co | e may apply. If the part is an assembly with low<br>s accuracy and that such information is true an<br>ce of its products with European Union member<br>de independently verified such information. Ho<br>neir contributions to the part, and those certifica | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>d correct to the best of its knowledge and belief,<br>er state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>ations are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |  |  |
| RoHS Declaration * 4 - Item(   | s) does not contain RoHS restricted subst  | ances per the definition above except for sele  | ected exempt  | ions Supplier Acceptance  | * Accepted  |  |  |  |  |  |  |  |
| Exemption: 7a: Lead in high melting temp   | erature type solders (i.e. lead based sol  | der alloys containing 85% by weight or m  | ore lead).  |   |   |  |  |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU   |   |   |   |   |  |  |  |  |  |  |  |
| Declaration Signature  |  |   |   |   |   |  |  |  |  |  |  |  |
| Instructions: Complete all of the required<br>Requester) and click on Submit Form to h   |  |   | e drop-dowi   | a. This will display the signature area. Digita   | lly sign the declaration (if required by the  |  |  |  |  |  |  |  |
| Supplier Digital Signature   | astislav Drska   | Le  |   |   |   |  |  |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

| Homogeneous Material | Weight | Unit of Measure | Level    | Substance                  | CAS        | Exempt | Weight    | Unit of Measure |
|----------------------|--------|-----------------|----------|----------------------------|------------|--------|-----------|-----------------|
| Die                  | 32.0   | mg              | Supplier | Silicon (Si)               | 7440-21-3  |        | 32        | mg              |
| Die Attach Solder    | 35.025 | mg              | Supplier | Silver (Ag)                | 7440-22-4  |        | 0.8756    | mg              |
|                      |        |                 | А        | Lead (Pb)                  | 7439-92-1  | 7a     | 32.3981   | mg              |
|                      |        |                 | Supplier | Tin (Sn)                   | 7440-31-5  |        | 1.7512    | mg              |
| Lead Frame           | 3612.9 | mg              | Supplier | Iron (Fe)                  | 7439-89-6  |        | 3.6129    | mg              |
|                      |        |                 | Supplier | Copper (Cu)                | 7440-50-8  |        | 3608.2031 | mg              |
|                      |        |                 | Supplier | Phosphorus (P)             | 7723-14-0  |        | 1.0839    | mg              |
| Mold Compound-Black  | 1740.0 | mg              | Supplier | Ortho Cresol Novolac Resin | 29690-82-2 |        | 130.5     | mg              |
|                      |        |                 | Supplier | Carbon Black (C)           | 1333-86-4  |        | 8.7       | mg              |
|                      |        |                 | Supplier | Fused Silica (SiO2)        | 60676-86-0 |        | 1522.5    | mg              |
|                      |        |                 | Supplier | Phenolic Resin (Novolac)   | 9003-35-4  |        | 78.3      | mg              |
| Plating              | 31.0   | mg              | Supplier | Tin (Sn)                   | 7440-31-5  |        | 31        | mg              |
| Wire Bond - Al       | 6.0    | mg              | Supplier | Aluminum (Al)              | 7429-90-5  |        | 6         | mg              |